

FCL Components Wireless Modules

Bluetooth® Ver. 4.1 Module (Blank Version)

(Central/Peripheral)

MBH7BLZ01A-109008 - *Not for New Design - July 2024*

MBH7BLZ02A-109009 - *Discontinued - March 2025*

Bluetooth Core Specification Version 4.1 (Bluetooth low energy) conforming peripheral "blank" modules.

Overview

Bluetooth Core Specification Version 4.1 (Bluetooth low energy) conforming peripheral "blank" modules (separation of protocol stack and application code), with Central/Peripheral function available.

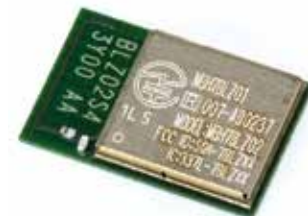


RoHS compliant

"Blank" module

Features

- "Blank" module: user can develop own unique application codes
- Based on Nordic Semiconductor nRF51822 SoC Rev. 3
- All 31 GPIO pins are allocated to the module
- Separation of protocol stack and application code
- Assurance that the protocol stack is fully tested and can't be corrupted by application software development
- Implement your unique profiles and application code



MBH7BLZ02A-109009



MBH7BLZ01A-109008

Item		Specifications
Part number	MBH7BLZ01A-109008	MBH7BLZ02A-109009
Antenna	None	Patterned antenna
Bluetooth technology	Conforms to <i>Bluetooth</i> Core Specification Version 4.1 (single mode low energy radio)	
RAM	32KB	
Transmit power	+4 dBm max.	
Receiver sensitivity	-88 dBm typical	
Interface	UART, SPI, I ² C, GPIO	
Crystal oscillator	Embedded	
Power supply	1.9 V to 3.6 V corresponds to LDO mode	
Power consumption (current)	Tx mode	10.5mA typical (+0dBm)
	Rx mode	13mA typical
Operating temperature	-25°C to +85°C (no condensation)	
Dimensions	10.5 x 9.2 x 1.6 mm	15.7 x 9.8 x 2.0 mm
Mounting method	SMD	
Certifications	Radio Act (Japan) / QDID	FCC / IC / CE / Radio Act (Japan)/ QDID

Note: *Bluetooth* SIG registration is required to use this module's QDID.
Available free RAM space: 20KB

Evaluation kit

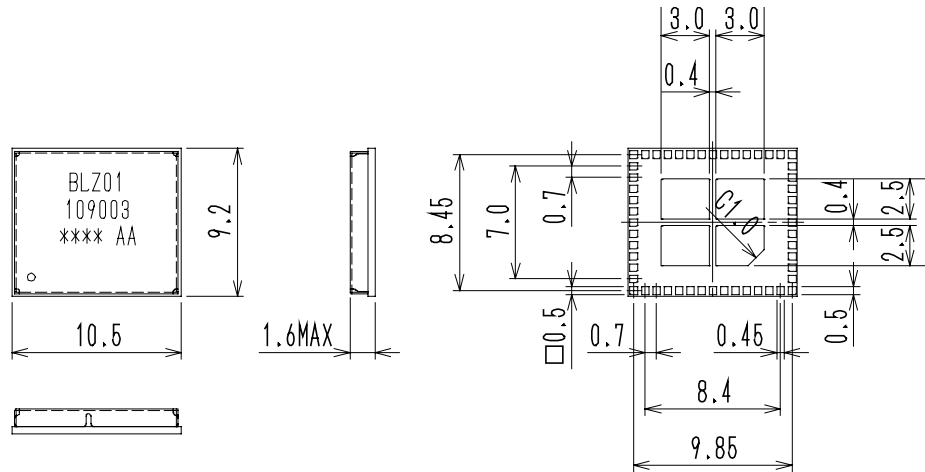
Part number	Details	MOQ
MBH7BLZ02A-EB1-KIT-2	Evaluation kit	1 set

Upper layer protocol & application development tool

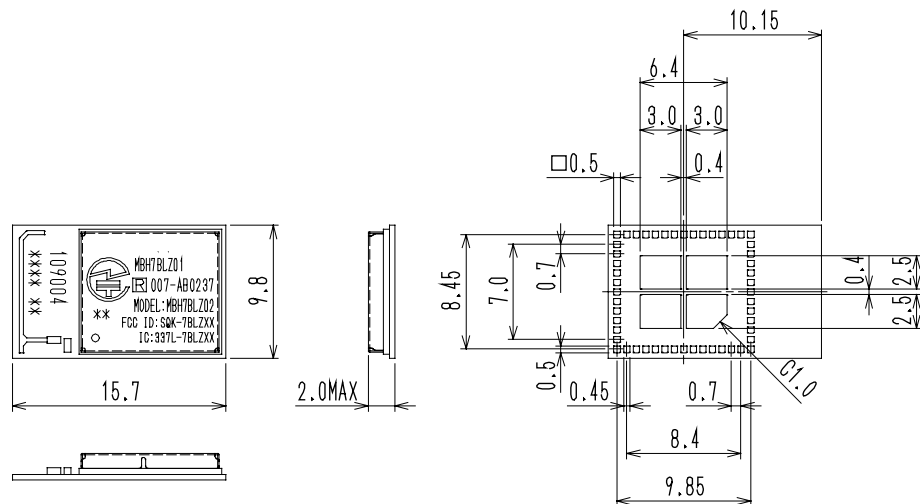
Please download* the following software from Nordic Semiconductor:
www.nordicsemi.com
• Software Development Kit ("SDK")

■ Dimensions

MBH7BLZ01A-109008



MBH7BLZ02A-109009



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